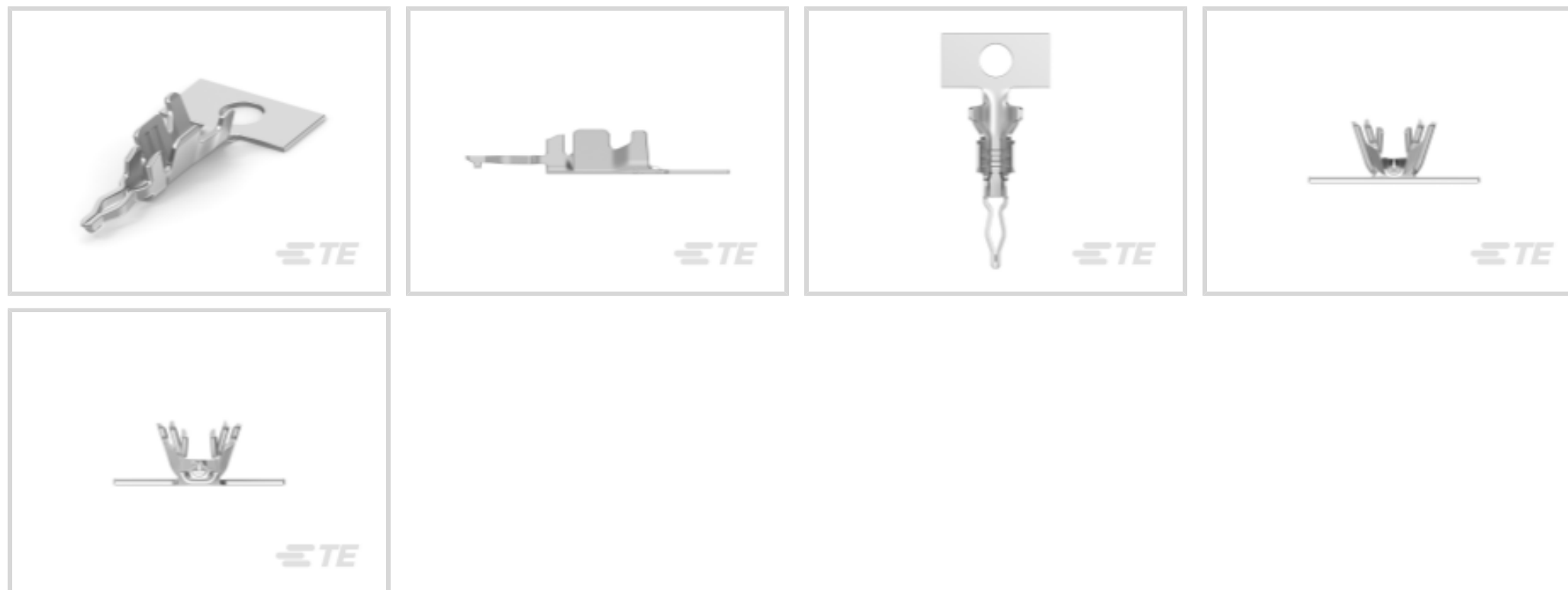




Connectors > PCB Connectors > Wire-to-Board Connectors > Wire-to-Board Connector Contacts



Contact Type: **Pin**

Connector System: **Wire-to-Board**

Wire Size: **.12 – .35 mm<sup>2</sup>**

Contact Mating Area Plating Material: **Tin**

## Features

### Product Type Features

Connector System	Wire-to-Board
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board

### Contact Features

Mating Tab Width	.5 mm[.02 in]
Contact Type	Pin
Contact Mating Area Plating Material	Tin
Contact Current Rating (Max)	4 A

### Mechanical Attachment

Connector Mounting Type	Cable Mount (Free-Hanging)
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### Dimensions

PCB Hole Diameter	.79 mm[.031 in]
Wire Size	.12 – .35 mm <sup>2</sup>

### Usage Conditions

Operating Temperature Range	-40 – 105 °C[-40 – 221 °F]
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### Operation/Application

Circuit Application	Signal
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### Packaging Features

Packaging Method	Strip
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### Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2022 (224) Candidate List Declared Against: JUNE 2022 (224) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Not reviewed for solder process capability

#### Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

### Compatible Parts

 <p>TE Part # 172520-6 6P 2.5MM MINI AMP-IN HDR HSG</p>	 <p>TE Part # 172782-5 LOW PROFILE MINI AMP-IN</p>	 <p>TE Part # 172520-2 2P 2.5MM MINI AMP-IN HDR HSG</p>	 <p>TE Part # 172781-4 LOW PROFILE MINI AMP-IN (AWG#30-#26)Y-TY</p>
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## Documents

### Product Drawings

#### LOW PROFILE MINI AMP-IN SM

English

### CAD Files

#### 3D PDF

3D

#### Customer View Model

[ENG\\_CVM\\_CVM\\_2238190-1\\_A.2d\\_dxf.zip](#)

English

#### Customer View Model

[ENG\\_CVM\\_CVM\\_2238190-1\\_A.3d\\_igs.zip](#)

English

#### Customer View Model

[ENG\\_CVM\\_CVM\\_2238190-1\\_A.3d\\_stp.zip](#)

English

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.